




Power MOSFETS

DATASHEET

LM20210PLJ3A

P-Channel
Enhancement Mode MOSFET

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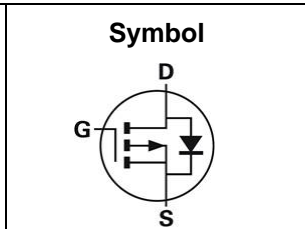
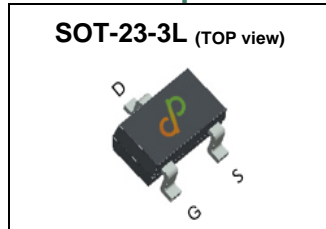


Quality Management Systems

ISO 9001:2015 Certificate

P-Channel Enhancement Mode MOSFET

Pin Description



Product Summary

Symbol	P-Channel	Unit
V_{DSS}	-20	V
$R_{DS(ON)-Max}$	24	m Ω
I_D	-6	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM20210PLJ3A	SOT-23-3L	Tape & Reel	3000 / Tape & Reel	03□□□

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	±8		
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
$I_{DM}^{①}$	Pulse Drain Current Tested	T _A =25°C	-15	A
I_D	Continuous Drain Current	T _A =25°C	-6	A
		T _A =70°C	-4.8	
P_D	Maximum Power Dissipation	T _A =25°C	1.25	W
		T _A =70°C	0.8	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	-15	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.1mH	11	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit	
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State	100	°C/W

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

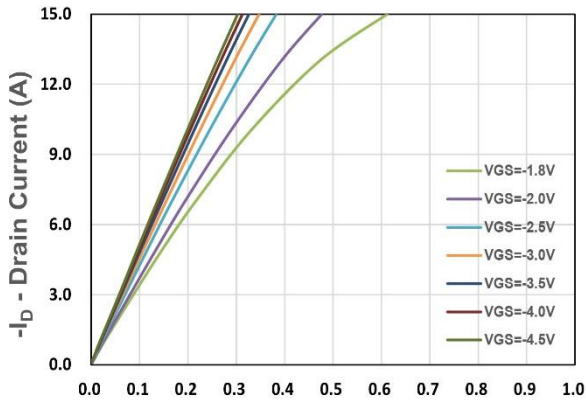
P-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V	-	-	-1	uA
V_{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-0.3	-0.5	-0.75	V
I_{GSS}	Gate Leakage Current	V _{GS} =±8V, V _{DS} =0V	-	-	±100	nA
R_{DS(ON)}^④	Drain-Source On-state Resistance	V _{GS} =-4.5V, I _{DS} =-6A	-	20	24	mΩ
		V _{GS} =-2.5V, I _{DS} =-3.7A	-	24	31	
		V _{GS} =-1.8V, I _{DS} =-2A	-	28	42	
gfs	Forward Transconductance	V _{DS} =-3V, I _{DS} =-3A	-	16.3	-	S
Dynamic Characteristics^⑤						
R_G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	11.4	-	Ω
C_{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, Freq.=1MHz	-	1872	-	pF
C_{OSS}	Output Capacitance		-	193	-	
C_{rss}	Reverse Transfer Capacitance		-	164	-	
t_{d(ON)}	Turn-on Delay Time	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-1A, R _{GEN} =6Ω	-	8.1	-	nS
t_r	Turn-on Rise Time		-	21	-	
t_{d(OFF)}	Turn-off Delay Time		-	153.9	-	
t_f	Turn-off Fall Time		-	60	-	
Q_g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-6A	-	22.95	-	nC
Q_{gs}	Gate-Source Charge		-	3.95	-	
Q_{gd}	Gate-Drain Charge		-	4.83	-	
Source-Drain Characteristics						
V_{SD}^④	Diode Forward Voltage	I _{SD} =-3A, V _{GS} =0V	-	-0.7	-1.1	V
t_{rr}	Reverse Recovery Time	I _F =-3A, V _R =-10V	-	18.4	-	nS
Q_{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	8.3	-	nC

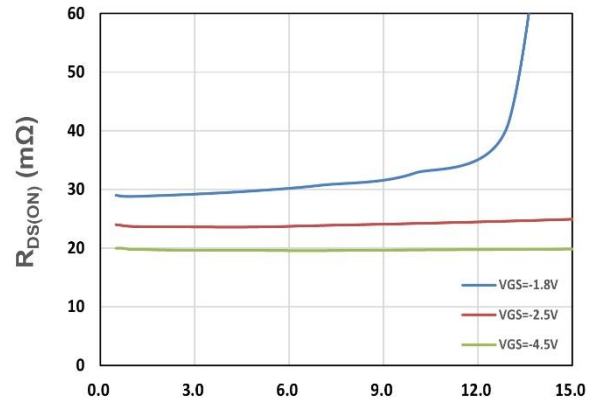
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

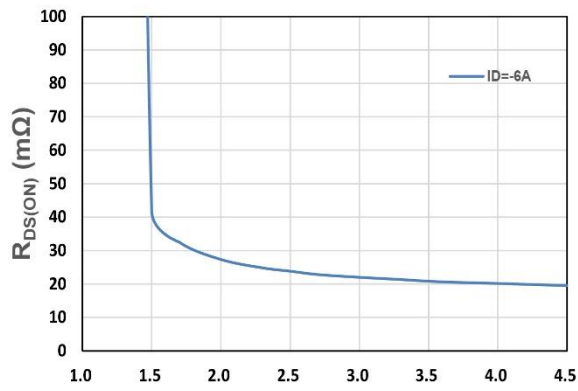
P-Channel Typical Characteristics



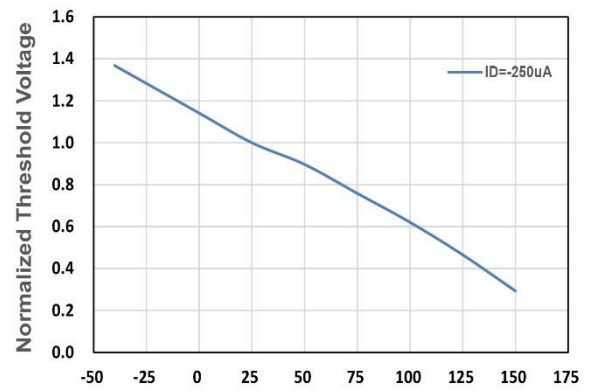
$-V_{DS}$ - Drain - Source Voltage (V)
Figure 1. Output Characteristics



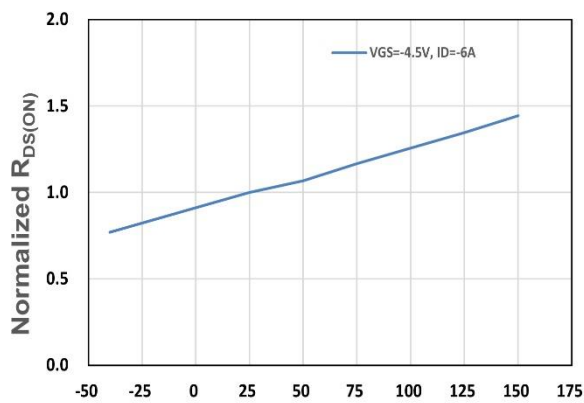
$-I_D$ - Drain Current (A)
Figure 2. On-Resistance vs. ID



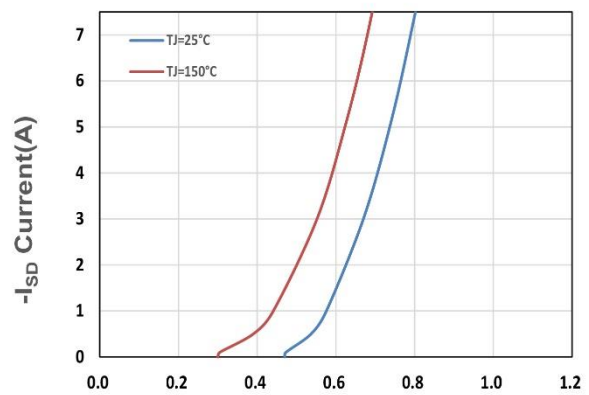
$-V_{GS}$ - Gate - Source Voltage (V)
Figure 3. On-Resistance vs. VGS



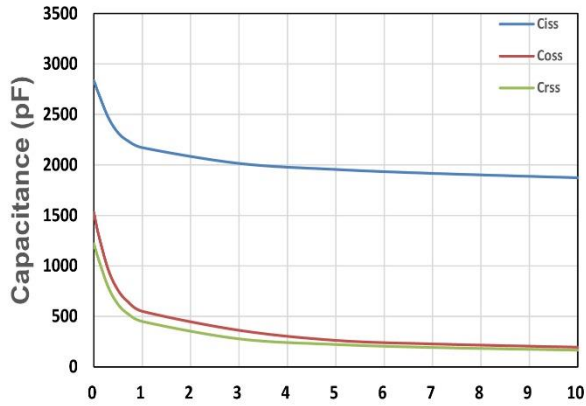
T_j , Junction Temperature(°C)
Figure 4. Gate Threshold Voltage



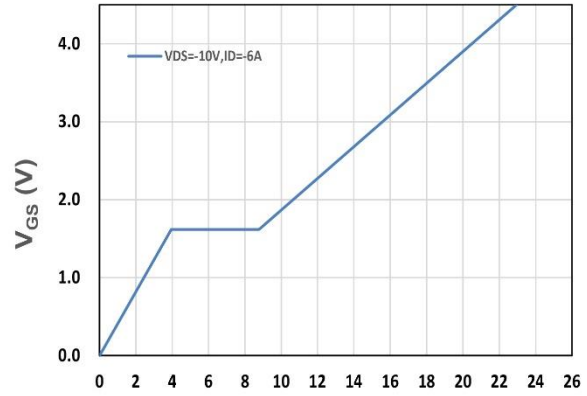
T_j , Junction Temperature(°C)
Figure 5. Drain-Source On Resistance



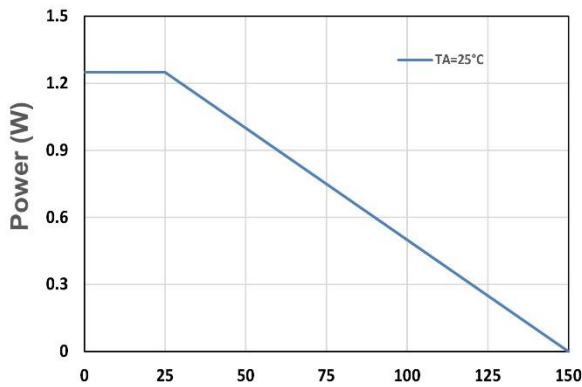
$-V_{SD}$, Source-Drain Voltage(V)
Figure 6. Source-Drain Diode Forward



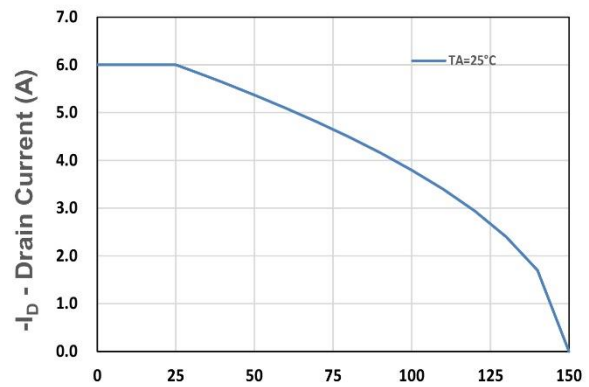
-V_{DS} - Drain - Source Voltage (V)
Figure 7. Capacitance



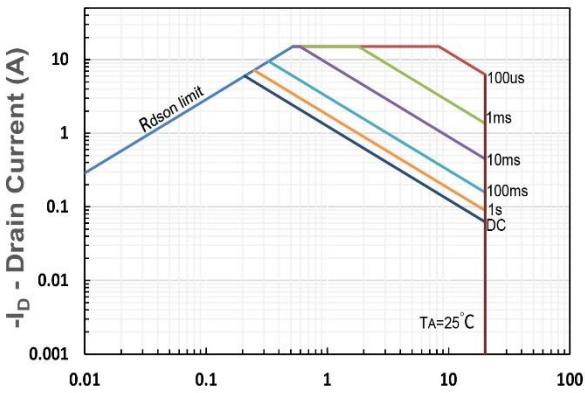
Qg, Total Gate Charge (nC)
Figure 8. Gate Charge Characteristics



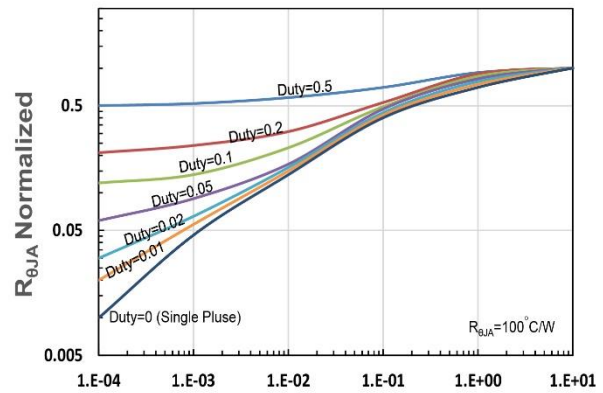
Tj - Junction Temperature (°C)
Figure 9. Power Dissipation



Tj - Junction Temperature (°C)
Figure 10. Drain Current



-V_{DS} - Drain-Source Voltage (V)
Figure 11. Safe Operating Area



t₁, Square Wave Pulse Duration (s)
Figure 12. R_{θJA} Transient Thermal Impedance